

## IN THE SPECIFICATION

Please insert the following new paragraph at page 18, between lines 16 and 17:

Fig. 8 is a cross-sectional view illustrating a state that a reinforcing material has been arranged on the molding surface of the top force.

Please replace the paragraph at page 18, lines 17-21, with the following rewritten paragraph:

Fig. [[8]] 9 is a cross-sectional view illustrating a state that a first molding material layer has been formed on the molding surface of a top force, and a second molding material layer has been formed on the molding surface of the bottom force.

Please delete the paragraph at page 18, lines 22-24, in its entirety.

Please replace the paragraph at page 24, line 21 to page 25, line 8, with the following rewritten paragraph:

In the embodiment illustrated, those formed in another region than the peripheral edge portion in the anisotropically conductive film 10A among the plurality of the conductive path-forming parts 11 serve as effective conductive path-forming parts 12 electrically connected to the target electrodes to be connected, for example, electrodes to be inspected in a circuit device 1, which is an object of inspection, and those formed in the peripheral edge portion in the anisotropically conductive ~~part~~ film 10A serve as non-effective conductive path-forming parts 13 that are not electrically connected to the target electrodes to be connected. The effective conductive path-forming parts 12 are arranged in accordance with a pattern corresponding to a pattern of the target electrodes to be connected.

Please replace the paragraph at page 40, line 25 to page 41, line 5, with the following rewritten paragraph:

As illustrated in Figs. 4 and 5, ~~frame-like spacers 54a, 54b each having an opening at a central position, and~~ a supporting body 71 having an opening 73 and positioning holes 72 ~~are~~ is first provided, and the supporting body 71 is fixed and arranged at a prescribed position of the bottom force 55 through the frame-like spacer 54b having an opening at a central position, as illustrated in Fig. 7. Further, the frame-like spacer 54a having an opening at a central position is arranged on the supporting body 71.

Please replace the paragraph at page 44, lines 16-26, with the following rewritten paragraph:

According to such a production process, the first molding material layer 61a containing the reinforcing material and formed on the molding surface of the top force ~~54~~ 50 is stacked on the second molding material layer 61b formed on the molding surface of the bottom force ~~56~~ 55, and the respective molding material layers are subjected to a curing treatment in this state, so that an anisotropically conductive connector 10 having an anisotropically conductive film 10A with the reinforcing material contained in only the surface layer portion 10B on one surface side can be advantageously and surely produced.

Please replace the paragraph at page 45, lines 3-9, with the following rewritten paragraph:

This inspection apparatus for circuit devices is equipped with a circuit board 5 for inspection having guide pins 9. On a front surface (upper surface in Fig. 1) of the circuit board ~~[[9]]~~ 5 for inspection, inspection electrodes 6 are formed in accordance with a pattern

corresponding to a pattern of semispherical solder ball electrodes 2 in a circuit device 1 that is an object of inspection.

Please replace the paragraph at page 55, lines 21-24, with the following rewritten paragraph:

For example, the pressurizing force-relaxing frame 65 may be such that the opening 66 is ~~greater~~ smaller in size than the anisotropically conductive film 10A in the anisotropically conductive connector 10 as illustrated in Fig. 24.

Please replace the paragraph at page 60, line 14 to page 61, line 2, with the following rewritten paragraph:

On the other hand, a spacer (54b) having a thickness of 0.1 mm and a rectangular opening of 20 mm by 13 mm in dimensions was arranged in alignment on a molding surface of the bottom force (55) of the mold, the above-described supporting support (71) was arranged in alignment on this spacer (54b), a spacer (54a) having a thickness of 0.1 mm and a rectangular opening of 20 mm by 13 mm in dimensions was further arranged in alignment on this supporting body (71), and the ~~third~~ molding material prepared was applied by screen printing, thereby forming a second molding material layer (61b), in which the conductive particles were contained in the liquid addition type silicone rubber, and the thickness of portions located on the non-magnetic substance layers (58) was 0.3 mm, in a cavity defined by the bottom force (55), spacers (54a, 54b) and supporting body (71).

Please replace the paragraph at page 71, line 20 to page 72, line 7, with the following rewritten paragraph:

An anisotropically conductive connector (10) according to the present invention was produced in the above-described manner. The anisotropically conductive film (10A) in the resultant anisotropically conductive connector (10) is in a form of a rectangle having dimensions of 20 mm by 13 mm, wherein the thickness of conductive path-forming parts (11) is 0.55 mm, the thickness of insulating parts ~~(12)~~ (15) is 0.5 mm, the number of conductive path-forming parts (11) is 288 (12 x 24), the diameter of each conductive path-forming part (11) is 0.45 mm, and the arrangement pitch (center distance) of the conductive path-forming parts (11) is 0.8 mm. Further, a ratio  $r_1/r_2$  of the opening diameter of the mesh to the average particle diameter of the conductive particles is 6.13.

Please replace the paragraph at page 72, line 12 to page 73, line 3, with the following rewritten paragraph:

An anisotropically conductive connector (10) according to the present invention was produced in the same manner as in Example 2 except that the spacer (54a) arranged on the molding surface of the top force (50) was changed to that having a thickness of 0.1 mm, and the spacer (54b) arranged on the molding surface of the bottom force (55) was changed to that having a thickness of 0.1 mm. The anisotropically conductive film (10A) in the resultant anisotropically conductive connector (10) is in a form of a rectangle having dimensions of 20 mm by 13 mm, wherein the thickness of conductive path-forming parts (11) is 0.40 mm, the thickness of insulating parts number ~~(12)~~ (15) is 0.35 mm, the number of conductive path-forming parts (11) is 288 (12 x 24), the diameter of each conductive path-forming part (11) is 0.45 mm, and the arrangement pitch (center distance) of the conductive path-forming parts

(11) is 0.8 mm. Further, a ratio  $r_1/r_2$  of the opening diameter of the mesh to the average particle diameter of the conductive particles is 6.13.

Please replace the paragraph at page 81, lines 5-9, with the following rewritten paragraph:

As a result, it was confirmed that the conductive path-forming parts of Anisotropically Conductive Connectors C1 to C3 according to Examples 2 ~~and 3~~ to 4 are scarcely deformed, and the conductive particles are retained in the conductive path-forming parts.

Please replace the paragraph at page 82, line 12 to page 83, line 3, with the following rewritten paragraph:

An anisotropically conductive connector (10) according to the present invention was produced in the same manner as in Example 2 except that the reinforcing material was changed to a sheet-like reinforcing material composed of mesh (thickness: 0.052 opening diameter: 72  $\mu\text{m}$ , opening rate: 50%) formed by polyarylate type composite fiber (fiber diameter: 30  $\mu\text{m}$ ). The anisotropically conductive film (10A) in the resultant anisotropically conductive connector (10) is in a form of a rectangle having dimensions of 20 mm by 13 mm, wherein the thickness of conductive path-forming parts (11) is 0.55 mm, the thickness of insulating parts ~~(12)~~ (15) is 0.40 mm, the number of conductive path-forming parts (11) is 288 (12 x 24), the diameter of each conductive path-forming part (11) is 0.45 mm, and the arrangement pitch (center distance) of the conductive path-forming parts (11) is 0.8 mm. Further, a ratio  $r_1/r_2$  of the opening diameter of the mesh to the average particle diameter of the conductive particles is 2.4.

Please replace the paragraph at page 83, line 10 to page 84, line 1, with the following rewritten paragraph:

An anisotropically conductive connector (10) according to the present invention was produced in the same manner as in Example 2 except that the reinforcing material was changed to a sheet-like reinforcing material composed of mesh (thickness: 0.073 mm, opening diameter: 114  $\mu\text{m}$ , opening rate: 51%) formed by polyarylate type composite fiber (fiber diameter: 45  $\mu\text{m}$ ). The anisotropically conductive film (10A) in the resultant anisotropically conductive connector (10) is in a form of a rectangle having dimensions of 20 mm by 13 mm wherein the thickness of conductive path-forming parts (11) is 0.55 mm, the thickness of insulating parts (~~(12)~~ (15)) is 0.40 mm, the number of conductive path-forming parts (11) is 288 (12 x 24), the diameter of each conductive path-forming part (11) is 0.45 mm, and the arrangement pitch (center distance) of the conductive path-forming parts (11) is 0.8 mm. Further, a ratio  $r_1/r_2$  of the opening diameter of the mesh to the average particle diameter of the conductive particles is 3.8.